

smartsystems integration

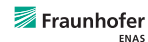
International Conference and Exhibition
on Integration Issues of Miniaturized Systems

Call for Papers

Cork, Ireland,
8–9 March 2017

smartsystemsintegration.com

Co-organizer:



Part of the activities of:



mesago
Messe Frankfurt Group

Invitation SSI 2017

More and more smart components and smart integrated systems enter into diverse innovative products and applications. They are key components and key technologies for industry 4.0 as well as internet of things and services. The application areas include not only smartphones with their advanced functionality but also monitoring systems for sustainable production, smart grid, smart home as well as support systems for senior citizens to guarantee their more independent lifestyle.

In the past 10 years the international Smart Systems Integration Conference and Exhibition has been successfully established by Prof. Thomas Gessner in Europe and worldwide. He developed this event into a unique podium of exchange of scientific ideas and a competitive international exhibition. It was a deep shock for us as we got the information that he suddenly passed away. Together with the committees, Mesago and the European Technology Platform on Smart Systems Integration EPoSS, we will continue these efforts to ensure the further success of this conference.

The overall topic for the keynote sessions of the SSI2017 are emerging technologies for the internet of things and industry 4.0. In the sessions we will continue to address application-oriented topics like smart mobility, smart health, smart energy, smart production and smart society. Moreover, innovative smart systems, their manufacturing technologies as well as issues of integration, embedding and software are also in the focus of the conference. Additionally, we will address business creation of smart systems, e.g. market trends or ecosystems for smart solutions.

On behalf of the committee, the Co-Chair – Dr. Guenter Lugert of Siemens AG and Chairman of EPoSS Executive Committee – and the local Co-Chairs from Ireland – Dr. Eric Moore, (University College Cork, Tyndall National Institute) and Ray Speer (Analog Devices) – I am looking forward to receiving your application or scientific oriented submission.

Prof. Dr. T. Otto

Fraunhofer Institute for Electronic Nano Systems ENAS
Conference chair Smart Systems Integration 2017

Conference topics 2017

A. Applications

- A01 Smart mobility
- A02 Smart health
- A03 Smart energy
- A04 Smart society
- A05 Smart production

B. Hardware/Technologies

- B01 Design of smart integrated systems
- B02 Manufacturing of embedded micro and nano systems
- B03 Advanced micro and nano technologies
- B04 New materials for nano structures and devices
- B05 Smart low cost approaches including Roll-to-Roll technologies and printed functionalities
- B06 Smart test and reliability of components and systems
- B07 System integration: 3D integration, interconnect technologies and packaging

C. Software for smart integrated systems

- C01 Embedded software
- C02 Stand-alone application software

D. Business creation of Smart Systems

- D01 Embedded software
- D02 Perspectives of Smart Systems
- D03 Ecosystems for Smart Solutions
- D04 SME success stories

Special topics

Emerging technologies for IoT and Industry 4.0

Smart Systems Integration International Conference and Exhibition

- Focuses on complex systems in consideration of the components,
- Is application-oriented,
- Close to the industry and
- Shows the potential of research and development activities worldwide.

At a glance

Highlight your expertise
at the SSI conference with
concurrent exhibition!

Date	8–9 March 2017
Conference Hours	Wednesday 09:00 hrs–17:35 hrs Thursday 09:00 hrs–16:15 hrs
Venue	Radisson BLU Hotel & Spa Cork Ditchley House – Little Island Little Island Business Park Cork, Ireland radissonblu.com/en/hotel-cork

Your advantages

- Present in front of a highly qualified audience.
- Exchange your experience with other experts.
- Build up your personal network.
- Benefit from maximum attention for your presentation due to extensive press work and several advertising activities.
- Take the opportunity to win the best paper/poster award.
- Participate in the extensive social program including Pre-conference field trip to Tyndall National Institute and conference dinner at Ballymaloe House.



Contact for further details

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Committee list

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Local co-chair

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Submission requirements

Conference language

English

Conditions of acceptance

Authors are expected to secure the registration fee of 315 EUR + VAT as well as travel and accommodation funding through their sponsoring organizations, before submitting abstracts. Full payment will be due once the submission has been accepted. Only original material should be submitted. Government and company clearance to present and publish should be finalized at the time of submission. Non-research based papers which attempt to promote commercial products cannot be submitted.

Selection process

The committee will review all submitted abstracts to maintain the high quality of the conference. Only papers submitted on time and addressing subjects which are topical and relevant to the conference will be considered for inclusion in the conference programme. Submitted papers may be selected for oral or poster presentations.

Oral and poster presentations

Oral presentations will be held in different sessions. The duration of each presentation should not exceed 25 minutes including 5 minutes for subsequent discussions. Poster authors will have the opportunity to present their posters during a special poster session and throughout the conference. All oral and poster presentations will be included in the conference proceedings.

Deadlines

Submission of abstracts

5 October 2016

Selection by committee

17 November 2016

Submission of full manuscripts

31 January 2017

Submission no later than 5 October 2016
at smartsystemsintegration.com

Impressions of SSI 2016
Exhibition and conference in Munich, Germany

